

Information Technology *for Engineering & Manufacturing*

Internet Commerce for Manufacturing: A National Testbed for the Electronic Commerce of Printed Circuit Assembly Services

Electronics manufacturers are contracting an increasing breadth of production processes to their suppliers—a trend which is global, but highly pronounced in North America. Initially the industry saw OEMs divest of component technologies such as PWB (Printed Wiring Board) fabrication. The shift towards outsourcing continues today with board assembly operations. This trend has led to the explosive growth of the OEM's first-tier suppliers, the Electronics Manufacturing Services industry. OEM's were well-positioned to deliver products when they controlled the entire production cycle, but in today's environment the entire supply chain is being challenged to respond quickly to fluctuating demand for products with shrinking shelf lives. The Internet Commerce for Manufacturing (ICM) project is working with industry to develop and demonstrate a suite of web-based standards to enable the electronics manufacturing supply chain to meet current time-to-market demands.

Presented by Barbara Goldstein

Ms. Goldstein currently serves as technical advisor on e-commerce to the Undersecretary of Technology, on loan from her usual position at the Electronics and Electrical Engineering Laboratory of NIST. She co-chairs National Electronics Manufacturing Initiative (NEMI) working groups and projects involved in IT interoperability within across the electronics supply chain. This work is integrated with NIST's ICM project, which she helped initiate in 1998. She previously developed and managed the Technologies for the Integration of Manufacturing Applications focused program. She has been active in several national and international standards committees, and has chaired an ANSI council on Tools and Technology, and an ISO Process Plants subcommittee.

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Internet Commerce for Manufacturing

A National Testbed for the Electronic Commerce of Printed Circuit Assembly Services

Barbara Goldstein

Electronics & Electrical Engineering Laboratory

Printed Circuit Assembly Trends

- **Paper-intensive information exchange and old/incomplete standards.**

An Electronics Manufacturing Service (EMS) provider can spend an entire day extracting needed data from a customer (OEM).

Impact: Poor information exchange reduces thin EMS profit margins (~ 3%).

- **Manufacturers guess on 80% of customer requirements.**

- < 20% of new customers provide complete data
- < 60% of existing customers provide complete data
- 0% of customers provide data that requires no modifications

Designs getting too sophisticated for CAM tools to reverse engineer.

Impact: Supply-chain forecasts are off 40%, on average.

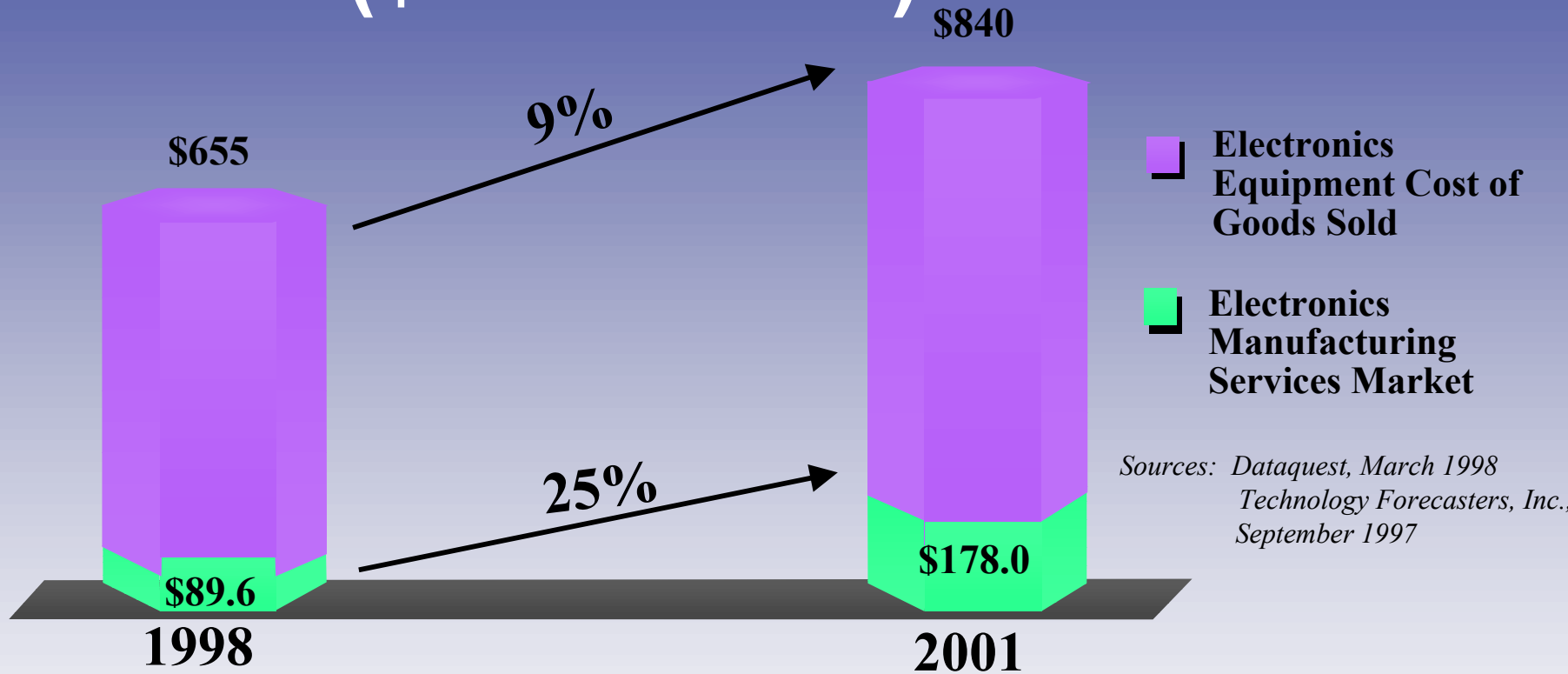
- **Outsourcing growth.**

OEM's are contracting out a greater percentage and breadth of production processes (e.g. mfg, design services, engineering, testing, distribution, ...).

Impact: Complex time-to-market and cost of outsourcing trade-off decisions.

Impact: Growing distributed supply web. Importance of efficient Supply Chain management, collaboration, alliances, partnerships.

The Outsourcing Trend Continues (\$ in Billions)

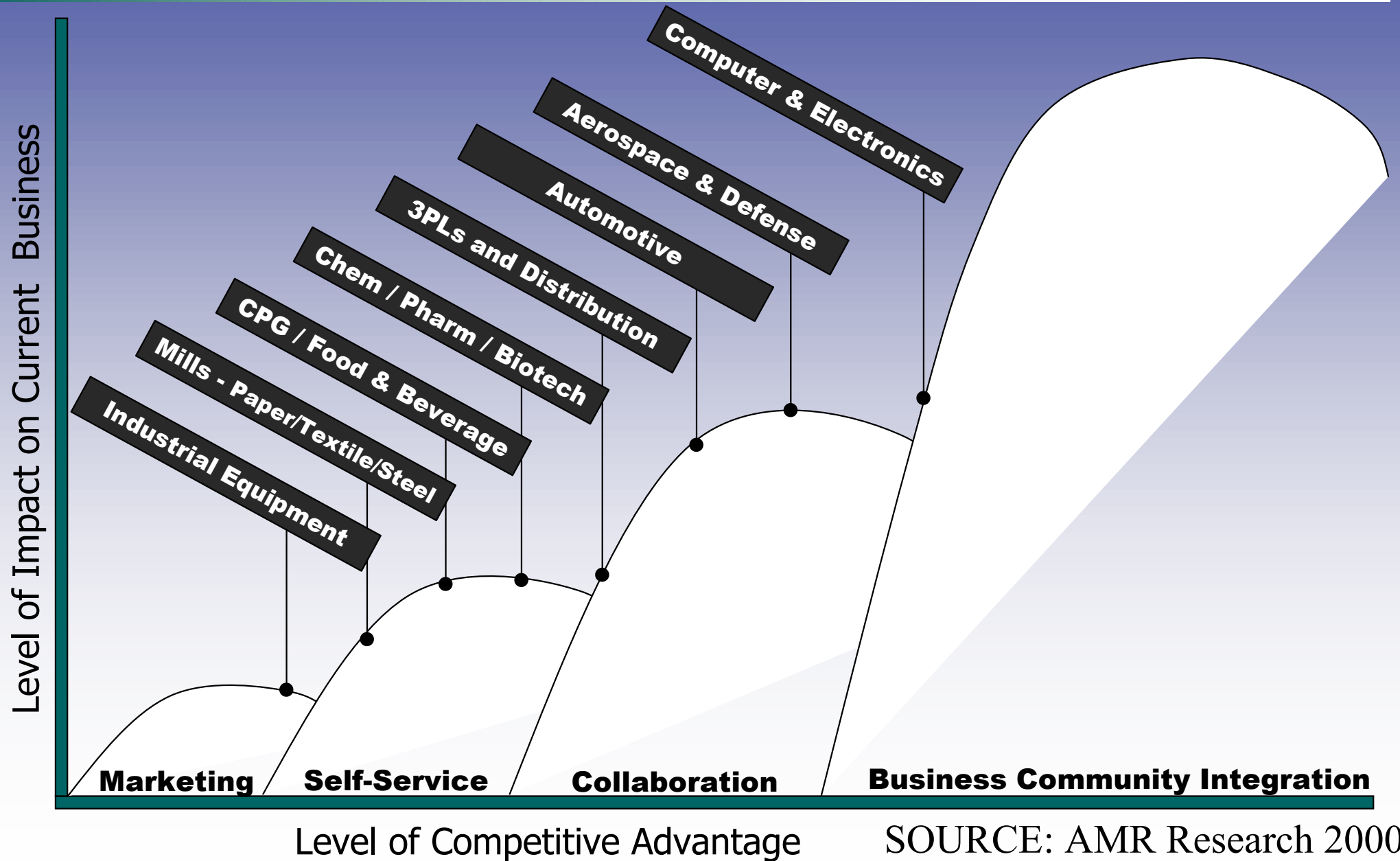


- The EMS industry is growing and migrating offshore.
- Companies must make Supply Chains function with the efficiency of a single enterprise.

More Electronics Industry Trends

- Assembly is becoming a commodity. Companies are competing on the strength of their supply chain.
- Industry is moving towards XML-based exchange standards in the near term, with an eye towards data vaulting and data sharing via Application Service Providers.
- Electronics leads other sectors in e-Business integration.

eBusiness Industry Leaders



e-manufacturing



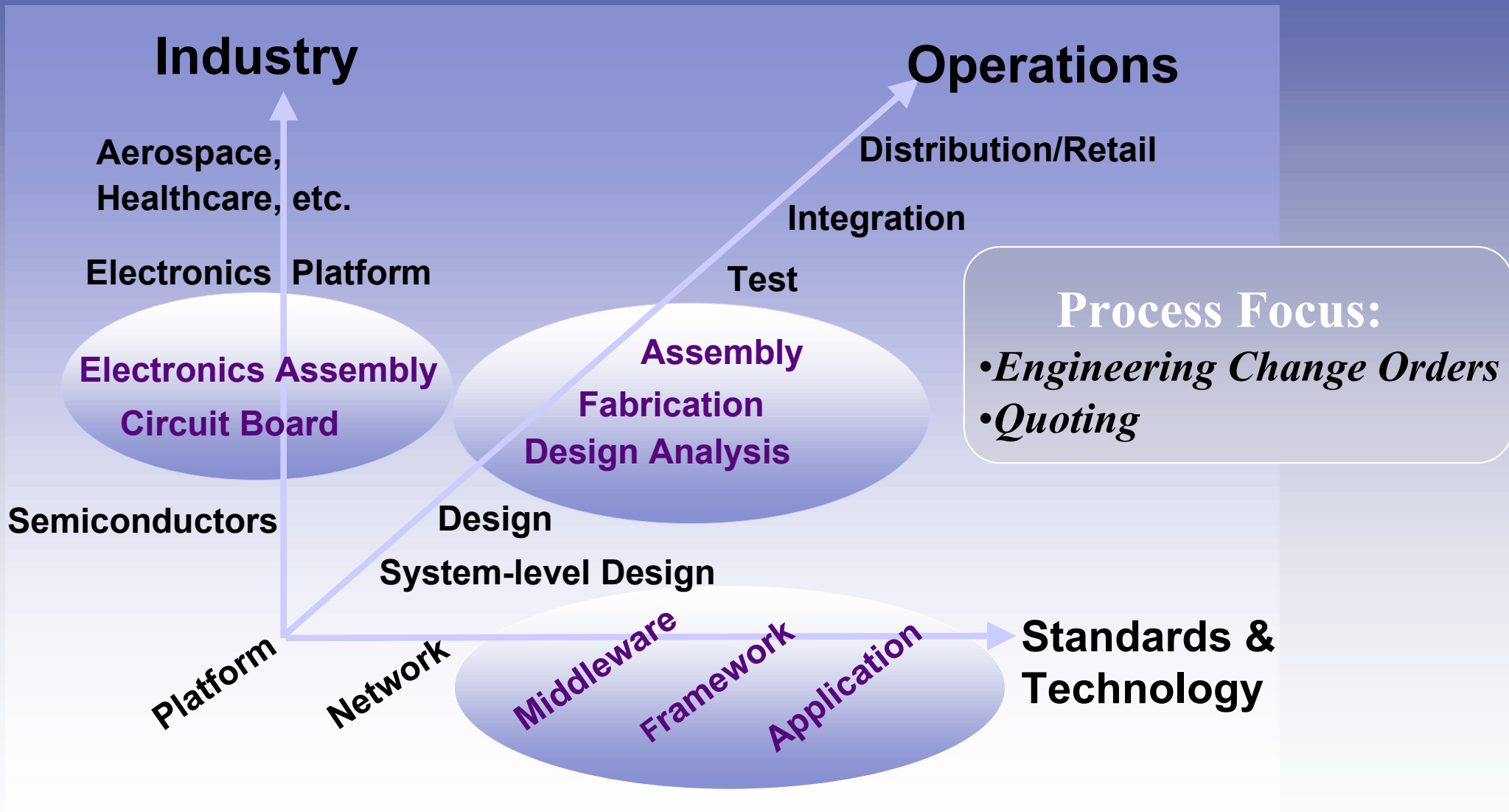
- **Electronic management of products and orders on the manufacturing floor.**
- **Direct transfer of customer order details to manufacturing personnel and equipment.**
- **Tight electronic connections to suppliers and partners providing visibility across the chain.**
- **Streamlined New Product Introduction (NPI) processes.**

SOURCE: AMR Research 2000

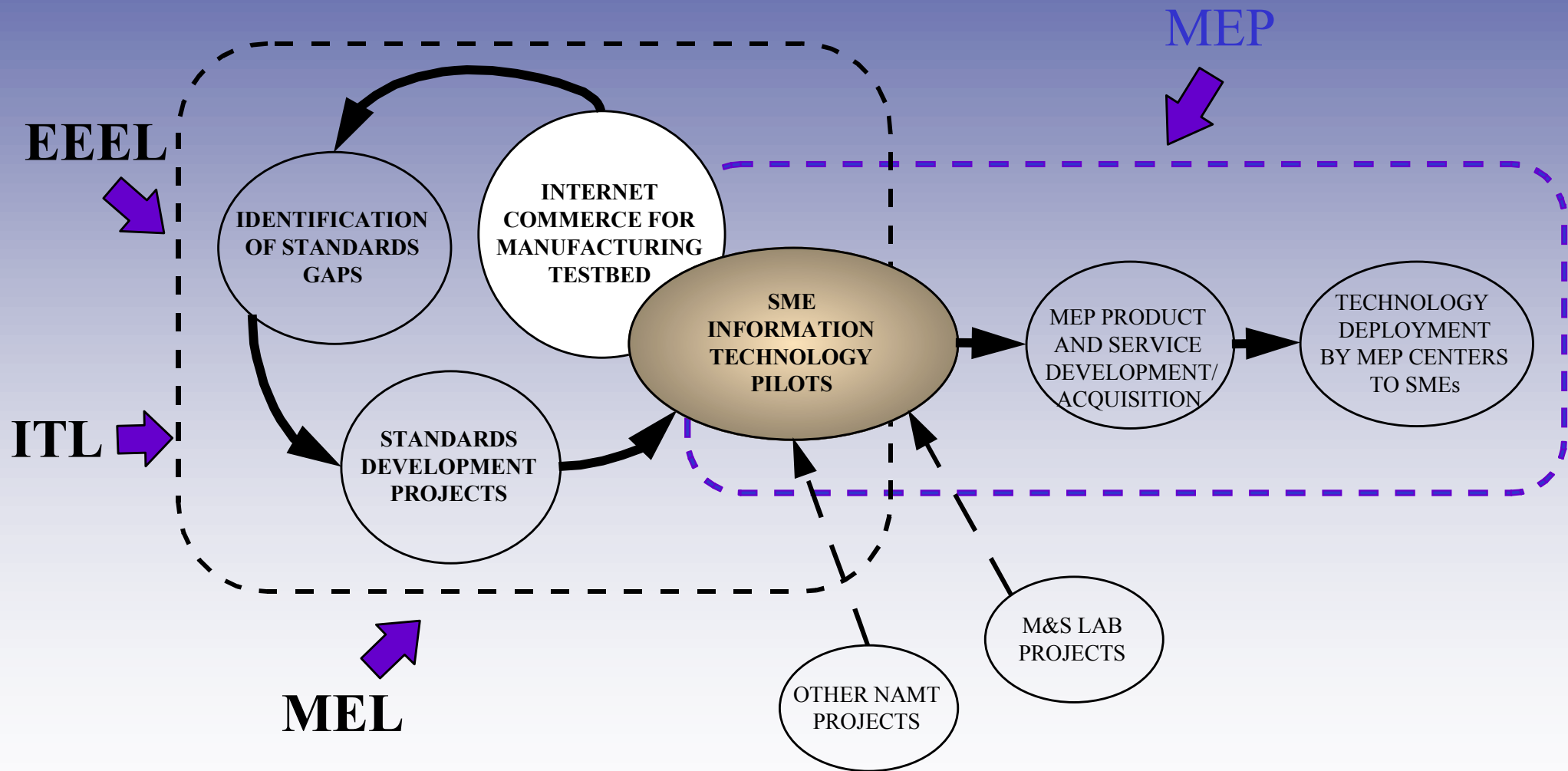
ICM Project Objectives

- Demonstrate integration of EC services with technical data interchange, to enhance the manufacturing and assembly process for electronic printed circuit boards.
- Enable exchange of build information and change notices for all supply-chain participants to support rapid decision-making and collaboration.
- Provide a flexible test-bed for industry and government to collaborate in testing and evaluating standards-based tools and integration technologies.

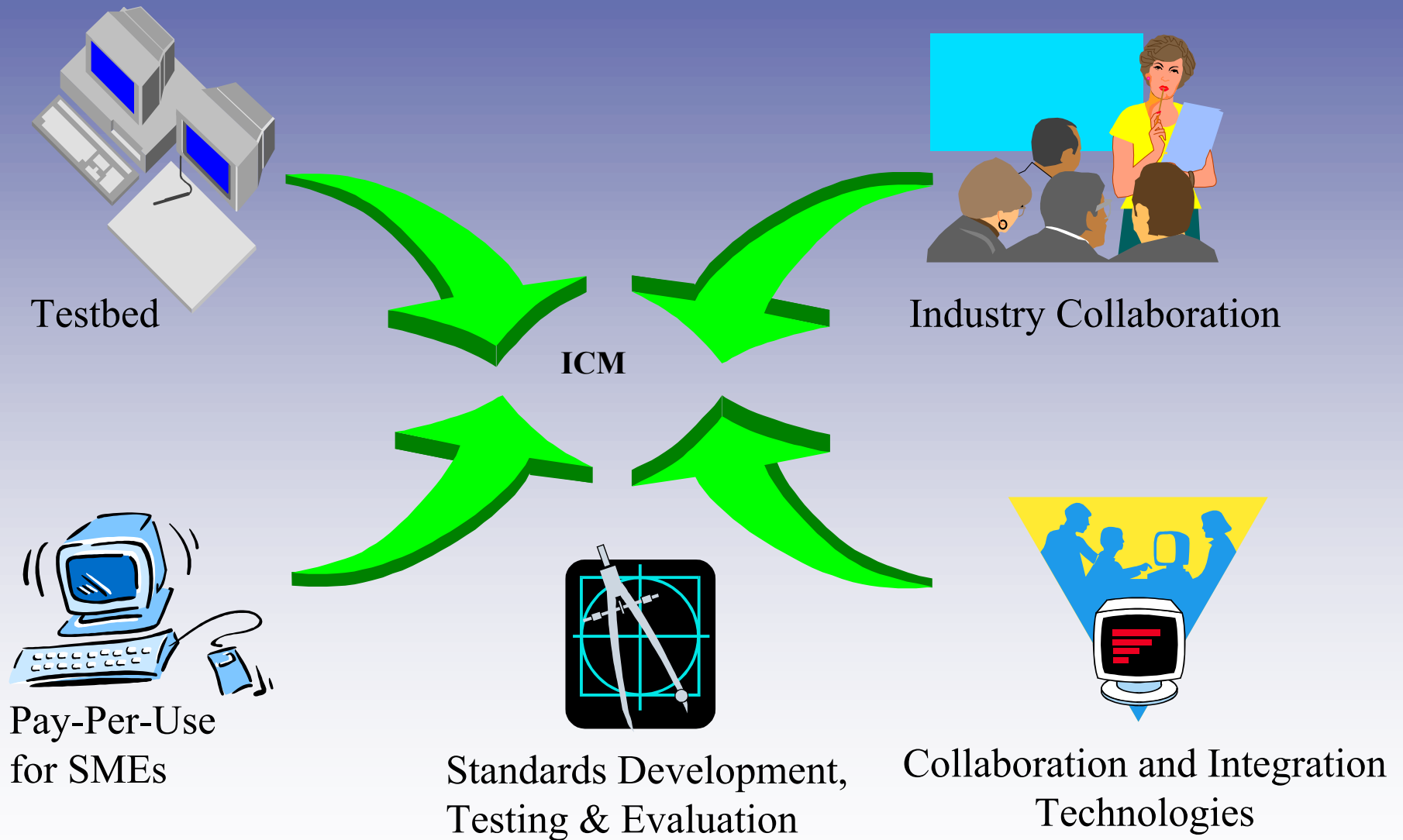
ICM Project Focus



Project Strategy

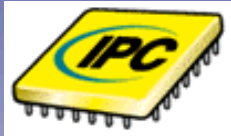


ICM Technical Approach

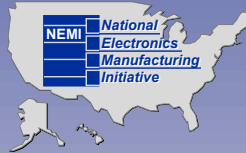


ICM Partners

Standards Development:



IPC GenCAM



NEMI Plug &
Play Factory



eCo
Working Group

Technology Development:



Software & Services:

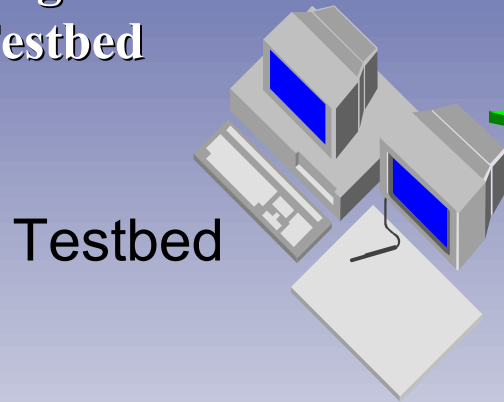


NIST

National Institute of Standards and Technology • Technology Administration • U.S. Department of Commerce

ICM Accomplishments

Demo Established
Boards Procured Electronically
Acting as 'OEM' in NEMI
Testbed



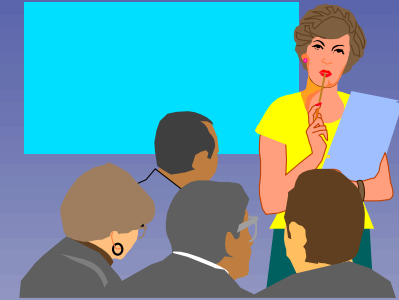
Testbed



Pay-Per-Use
for SMEs

Component Catalog
Manufacturability Analysis

Business Case
Activity Model
Process Model
Scenario Workshops
Architecture Workshop



Industry Collaboration

ICM/VITSS



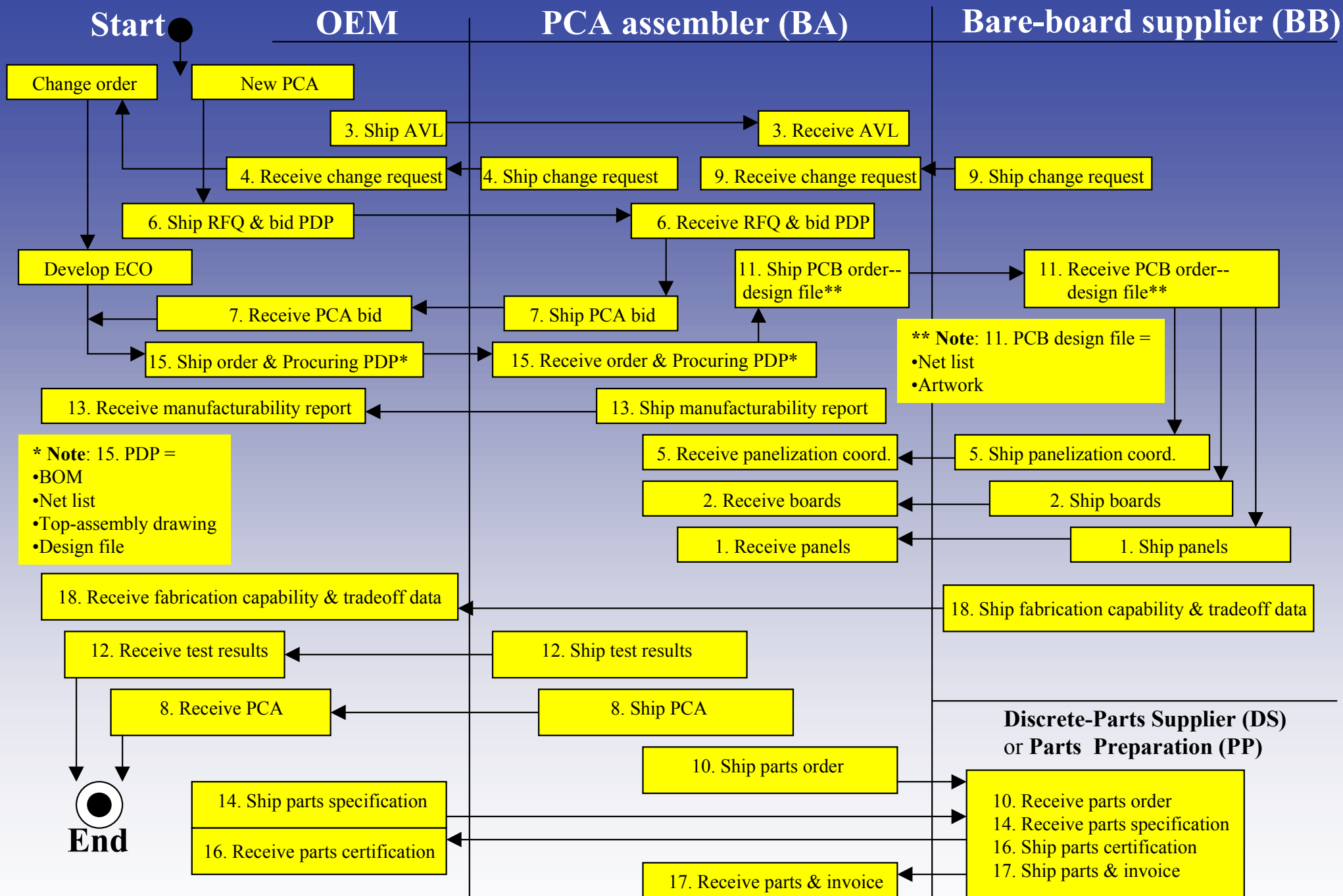
Standards Development,
Testing & Evaluation
eCo Working Group
IPC GenCAM Test Module
NEMI Standards



Collaboration Technologies

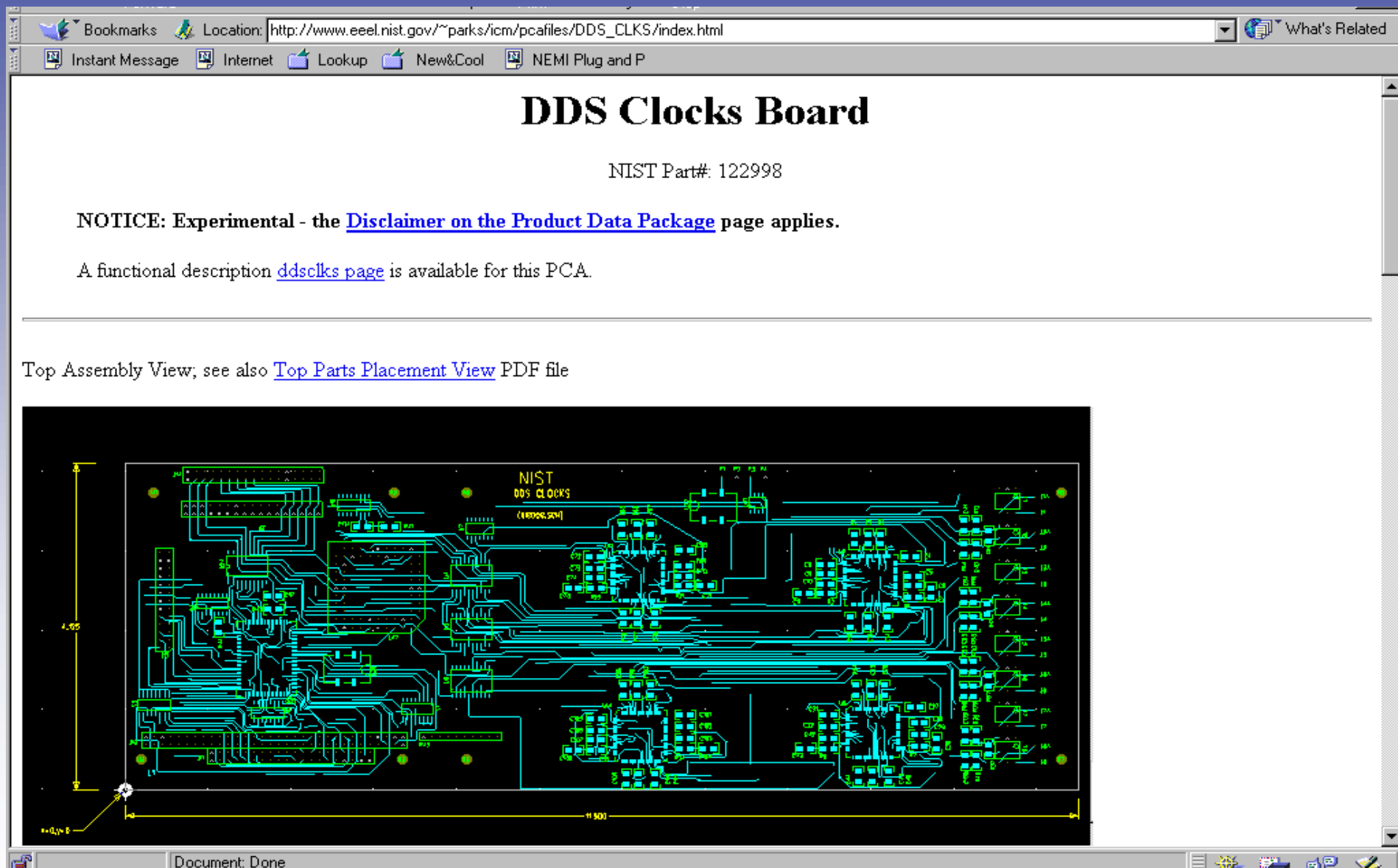
Quoting
Change Management
Agent framework &
business case being
developed





Transaction-Occurrence Model

“PCA on the Web”




Pay-per-Use: Manufacturability Analysis

Bookmarks Location: file:///D:/ICM/nist.dat/index.htm What's Related

Instant Message Internet Lookup New&Cool NEMI Plug and P

Design Analysis Archive

	Automata Design Inc. (ADI)		Part No. Bigdog2		Rev. -		Last Update: 2-11-1999	
Designer: NIST			Checked: A D I		Orig Date: 2-11-1999			
NET COMPARE	PADSTACK	CIRCUIT	MILLING	SOLDERMASK	COMPONENT MARKING	ASSEMBLY	PERFORMANCE	REFERENCE
Shorted Net1		Land - Land (Same Net)1			Mark - Mask1	Min Via to SMT (E-E)1	Reference Plane1	Reference 1
		Min - Web1			Mark - Mask2	Min Via to SMT (E-E)2	Reference Plane2	Reference2
		Min - Web2				Min Via to SMT (E-E)3	Reference Plane3	Reference3
		Min - Web3				Min Via to SMT (E-E)4	Reference Plane4	Reference4
		Min - Web4				Min Via to SMT (E-E)5	Reference Plane5	Reference5
						Min Via to SMT (E-E)6	Reference Plane6	Reference6
							Reference Plane7	Reference7
							Reference Plane8	Reference8
							Reference Plane9	Reference9

Document: Done


Pay-per-Use: Manufacturability Analysis

Bookmarks Location: file:///D:/ICM/nist.dat/cad_sht1.htm What's Related

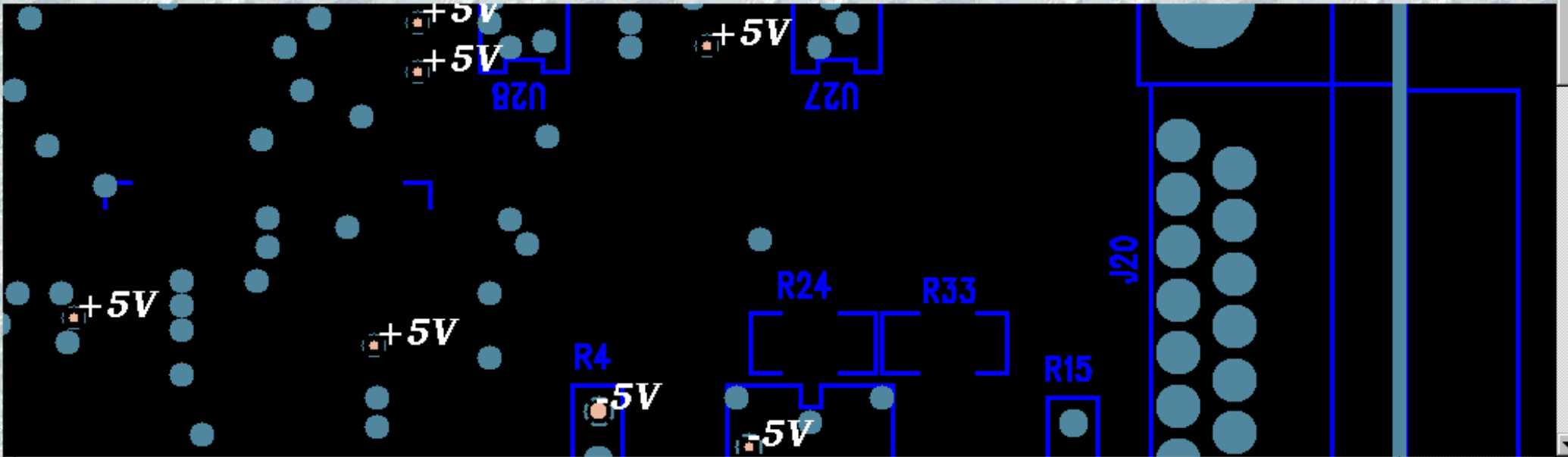
Instant Message Internet Lookup New&Cool NEMI Plug and P

Design Analysis Archive

[Return to Index Page](#)

	Automata Design Inc. (ADI)	Part No. Bigdog2	Rev. -	Orig Date: 2-11-1999
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Violation Type	NET	Layer
Shorted Net-1	-5V, +5V,	1 (Top Circuit), 3 (Plane), 4 (Bottom Circuit), 7 (Top Marking), 9 (Plated Thru Holes),



Document: Done

IPC GenCAM



overview

documentation

supporters

software

training

forum

SOFTWARE

- VIEWS
- DFM
- CONVERTERS
- EDITING
- COMPLIANCE**

GenCAM Conformance Test Module 0.5 (alpha) for IPC-2511A

The conformance test module (CTM) has been updated to parser data files for the IPC-2511A (proposal) for the GenCAM standard.

A [GenCAM example](#) that conforms to the 2511A specification is available. This file contains a couple dozen IPC land patterns that were hand coded by Dieter Bergman.

First name:

Last name:

email:

Filename: **Browse...**

- ☐ Generate Annotated Output (file size grows by about 20X.)
- ☐ Echo file with line numbers

Send **Reset**

[Michael McLay](#)
Last modified: Mon Aug 23 16:24:55 EDT 1999

Collaboration Technology: Engineering Change Order

Rev: A **Unincorporated**

Images:

Image Description	File List	Checkout User	Checkout Date	Checkout Folder
-------------------	-----------	---------------	---------------	-----------------

Files:

File Description	File Name
Drill Files	dds-drill.zip
Gerber Files	dds-gerber.
Board Bottom View	dds_clks_b
Board Top View	dds_clks_t

Redline for Part 122998 [DDS CLOCKS BOARD]

BOM

Find N...	Qty	Item Number	Part Description	Ref Des	BOM Notes
0	1	410-314-1111 410-314-1112	ICD2053B ICD2053C	U21	
0	1	74LS221	74LS221	U18	
0	3	74LS377	74LS377	U4, U5, U6	
0	1	74LS74	74LS74	U7	
0	1	81F9205R470	710A	R42	
0	8	AD9762AR	AD9762	U12, U13, U15, U16, U2, U3, U9, U10	
0	7	CR1206-1K	CR1206	R1, R2, R21, R22, R31, R32, R8	

Save Close

Collaboration Technology: Checking Production Status


Bookmarks Location: <http://preserver.marc.gatech.edu/consoles/Anaheim/IndexAnaheim.html> What's Related

Instant Message Internet Lookup New&Cool NEMI Plug and P

Server push - fullsize image - Netscape

Server push

12:59:02 22-FEB-1999



Event Viewer


Console

Line Monitor - Netscape

MPM Screenpri
Name
Machine Status
DateTime
Enter Process Exit

VRMachine
Name
Machine Status
DateTime
Enter Process Exit

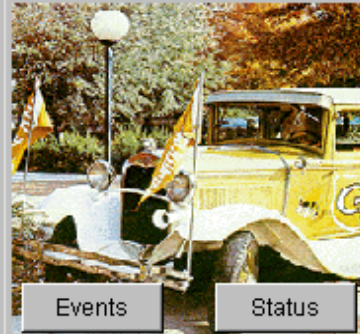
TimeStamp



Events Status

<<< Less EDS

Host: preserver.marc.gatech.edu Port: 8080 Connect



Events Status

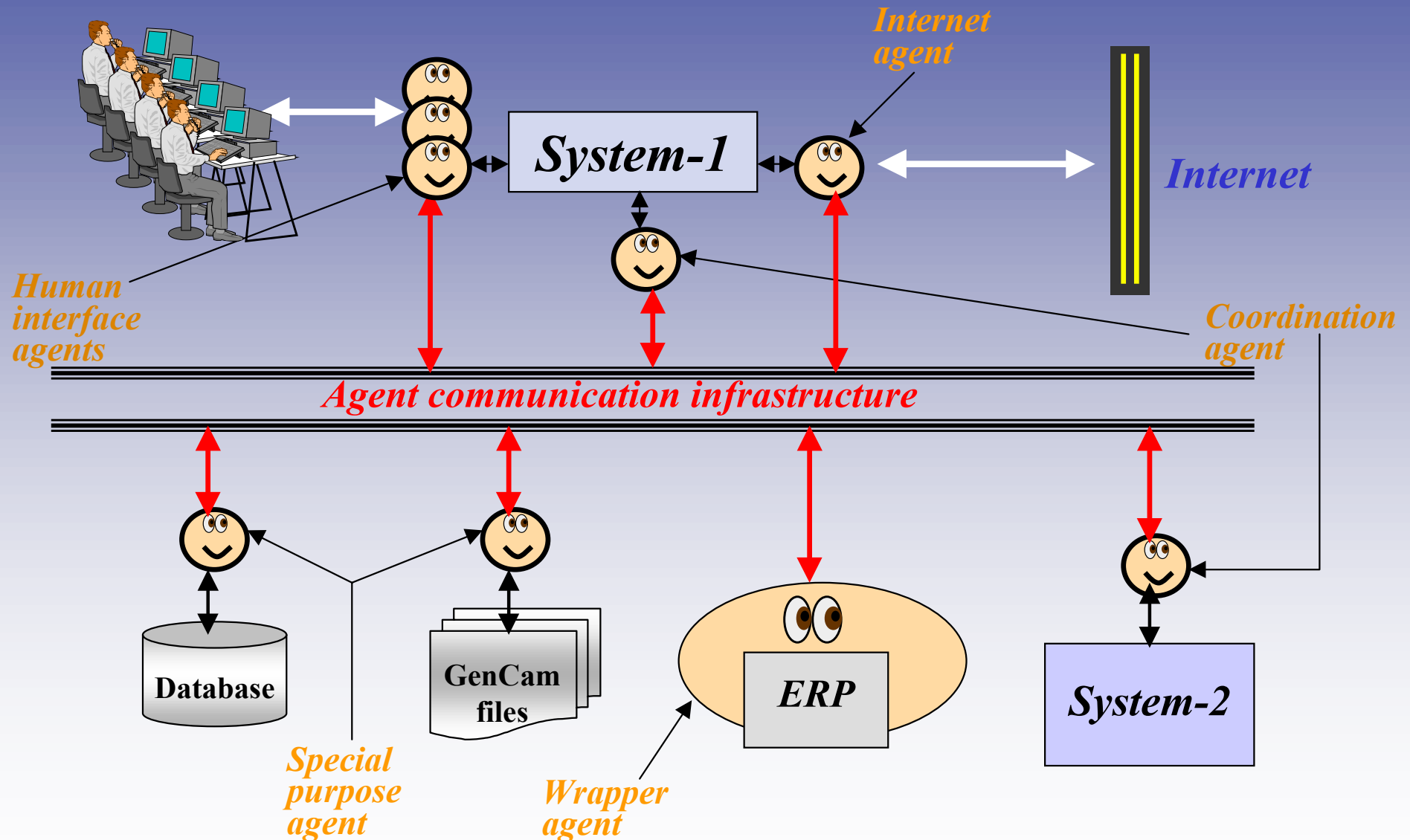
<<< Less EDS

Host: preserver.marc.gatech.edu Port: 8080 Connect

Javascript:DisplayAwindow5()

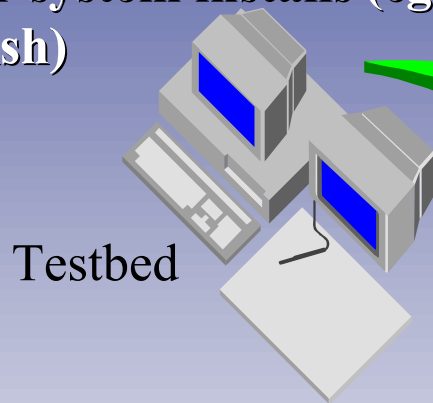
Agent-Based Information Exchange

Manager/designer/engineer/purchase agents



ICM Plans

Incorporate agents into Demo
Act as 'OEM' in NEMI Testbed
Further system installs (eg:
Netfish)



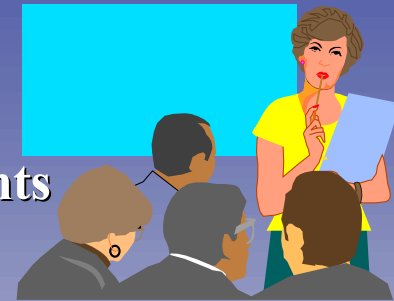
Testbed



Pay-Per-Use
for SMEs

ASP survey & analysis

Tech Deployment
to SMEs
Industry checkpoints



Industry Collaboration

ICM/VITSS



Standards Development,
Testing & Evaluation
GenCAM Test Module
NEMI Virtual Factory

RosettaNet Product Configuration
OAG Business Object Definitions



Collaboration Technologies

**Agent infrastructure: Business
case, implementation,
evaluation**

CONTACT US!

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Richard Korchack	rkorchak@nist.gov	301-975-8323

URL: <http://www.mel.nist.gov/namt/projects/icm/icm1.htm>

